



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## MAX14627/MAX14628

# Low-Power Headset Detectors with SEND/END Button Support

### General Description

The MAX14627/MAX14628 provide a simple solution for detecting the insertion and managing the operation of a 3.5mm stereo headset with a microphone. These devices integrate all circuitry needed to detect SEND/END button press events and generate required microphone bias voltages, and are fully compatible with Windows Mobile 7.

The devices need only three GPIOs from the host controller to select between call mode and standby mode, and monitor the SEND/END and jack insertion status. In call mode, the low-noise LDO is enabled to provide DC bias to the externally preamplified microphone. In standby mode, microphone low-power pulsing is enabled to reduce supply current while waiting for a SEND/END button press event. Two open-drain outputs signal the host controller when an insertion/removal or SEND/END button press event occurs. If a 3P headset without a microphone is inserted, the low-power pulsing can be disabled by setting the MODE input to high impedance.

The MAX14627 operates from a 2.5V to 5.5V input voltage supply and features an internal 2.2V LDO output, while the MAX14628 operates from a 3.1V to 5.5V voltage supply and features an internal 2.8V LDO output voltage. Both devices control jack insertion detection by monitoring a 3.5mm socket with a normally open jack insertion switch. Additionally, the MAX14628 features open microphone detection.

The MAX14627/MAX14628 are available in an 8-pin TDFN package, and are fully specified over the -40°C to +85°C extended temperature range.

### Benefits and Features

- ◆ **Versatile Jack Detection and Control**
  - ◇ **MODE Three-State Microphone Bias Control**
  - ◇ **MIC Switch Ground Detection (MAX14627)**
  - ◇ **MIC Switch Open and Ground Detection (MAX14628)**
- ◆ **Compatible with Windows Mobile 7 and Google Android**
  - ◇ **Microphone Button Press Detection**
- ◆ **High-Performance MIC Bias and Power Savings**
  - ◇ **No Pop-Up Noises**
  - ◇ **Ultra-Low Noise, High-PSRR MIC Bias**
  - ◇ **Low-Power MIC Idle Mode**
  - ◇ **Automatic Ultra-Low-Power Mode When Microphone Is Disabled**
- ◆ **PCB Space and Cost Savings**
  - ◇ **Integrated ±15kV ESD Protection (HBM) on DETIN and MIC Input Terminals**
  - ◇ **Small 8-Pin (2mm x 2mm) TDFN Package**

### Applications

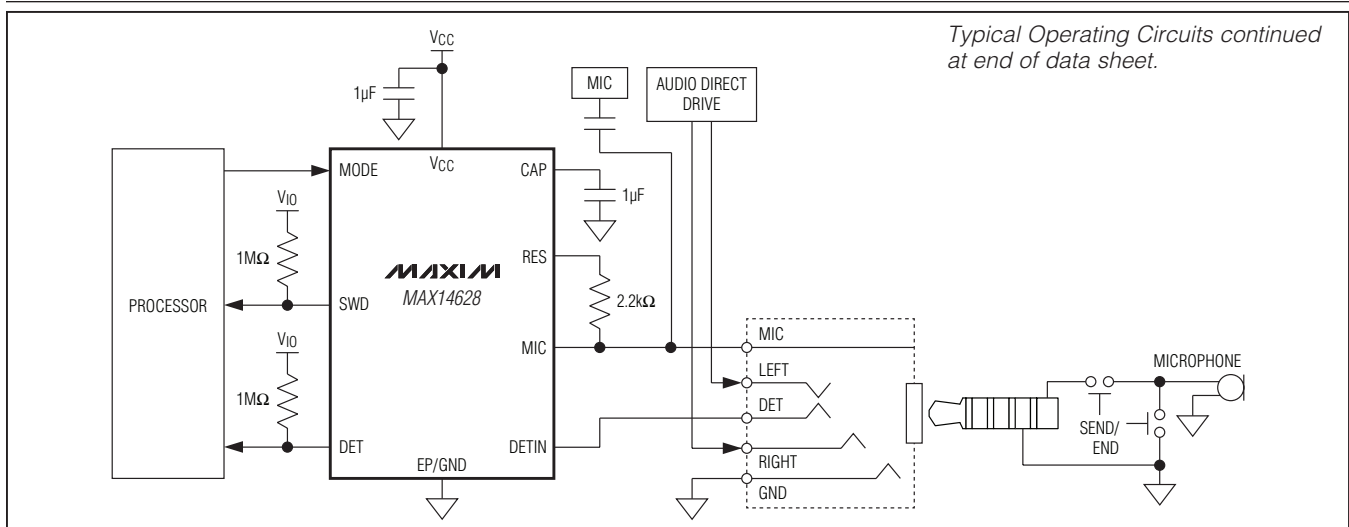
Cell Phones  
Portable Media Players  
Tablet/Laptop PCs

**Ordering Information** appears at end of data sheet.

For related parts and recommended products to use with this part, refer to [www.maxim-ic.com/MAX14627.related](http://www.maxim-ic.com/MAX14627.related).

Windows Mobile is a registered trademark of Microsoft Corporation.

### Typical Operating Circuits



# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### ABSOLUTE MAXIMUM RATINGS

(Voltages referenced to GND.)

$V_{CC}$ , MODE, SWD, DET .....-0.3V to +6V  
 CAP, MIC, RES..... -0.3V to ( $V_{CC}$  + 0.3V)  
 DETIN .....-6V to +6V  
 Continuous Current into Any Terminal .....  $\pm$ 100mA  
 Continuous Power Dissipation ( $T_A = +70^\circ\text{C}$ )  
 TDFN (derate 11.9mW/ $^\circ\text{C}$  above  $+70^\circ\text{C}$ ).....953.5mW

Operating Temperature Range .....-40 $^\circ\text{C}$  to +85 $^\circ\text{C}$   
 Junction Temperature .....+150 $^\circ\text{C}$   
 Storage Temperature Range.....-65 $^\circ\text{C}$  to +150 $^\circ\text{C}$   
 Lead Temperature (soldering, 10s) .....+300 $^\circ\text{C}$   
 Soldering Temperature (reflow) .....+260 $^\circ\text{C}$

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### PACKAGE THERMAL CHARACTERISTICS (Note 1)

TDFN

Junction-to-Ambient Thermal Resistance ( $\theta_{JA}$ ) .....83.9 $^\circ\text{C}/\text{W}$       Junction-to-Case Thermal Resistance ( $\theta_{JC}$ ) .....37 $^\circ\text{C}/\text{W}$

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to [www.maxim-ic.com/thermal-tutorial](http://www.maxim-ic.com/thermal-tutorial).

### ELECTRICAL CHARACTERISTICS

( $V_{CC} = 2.5\text{V}$  to  $5.5\text{V}$  for MAX14627,  $V_{CC} = 3.1\text{V}$  to  $5.5\text{V}$  for MAX14628,  $C_{DETIN} < 100\text{pF}$ ,  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ , unless otherwise noted. Typical values are at  $V_{CC} = +3.6\text{V}$ ,  $T_A = +25^\circ\text{C}$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
<b>DC CHARACTERISTICS</b>							
Supply Voltage Range	$V_{CC}$	MAX14627		2.5		5.5	V
		MAX14628		3.1		5.5	
$V_{CC}$ Undervoltage-Lockout Threshold	$V_{CCUVLO}$	$V_{CC}$ rising		0.9	1.7	2.45	V
$V_{CC}$ Supply Current	$I_{CC}$	MAX14627, $V_{CC} = 2.8\text{V}$	MODE = low, DETIN = high			1.3	$\mu\text{A}$
			MODE = low, DETIN = low, $I_{MIC} = 300\mu\text{A}$			11.7	
			MODE = high, DETIN = low, $I_{MIC} = 300\mu\text{A}$			800	
			MODE = high-Z, DETIN = low			6.0	
		MAX14628, $V_{CC} = 3.3\text{V}$	MODE = low, DETIN = high			1.9	
			MODE = low, DETIN = low, $I_{MIC} = 300\mu\text{A}$			13.2	
			MODE = high, DETIN = low, $I_{MIC} = 300\mu\text{A}$			800	
			MODE = high-Z, DETIN = low			7.0	

# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### ELECTRICAL CHARACTERISTICS (continued)

( $V_{CC} = 2.5V$  to  $5.5V$  for MAX14627,  $V_{CC} = 3.1V$  to  $5.5V$  for MAX14628,  $C_{DETIN} < 100pF$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $V_{CC} = +3.6V$ ,  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DETIN Pullup Resistance	$R_{DETIN}$			1000		$k\Omega$
DETIN Series Resistance	$R_{DETININT}$			100		$k\Omega$
Negative Current from DETIN	$I_{NDETIN}$	$V_{DETIN} = -2V$			31	$\mu A$
MIC SEND/END Detection Threshold	$V_{MICTH\_LOW}$		$0.20 \times V_{BIAS}$	$0.22 \times V_{BIAS}$	$0.24 \times V_{BIAS}$	V
MIC Open Switch Detection Threshold	$V_{MICTH\_HI}$	MAX14628	$0.90 \times V_{BIAS}$	$0.94 \times V_{BIAS}$	$0.98 \times V_{BIAS}$	V
DETIN Detection Threshold	$V_{DETINTH}$	Falling edge	$\frac{1}{3} \times V_{CC}$	$\frac{1}{2} \times V_{CC}$	$\frac{2}{3} \times V_{CC}$	V
MODE Pullup Resistance for High-Z Detection	$R_{MODE\_HI}$			200		$k\Omega$
MODE Pulldown Resistance for High-Z Detection	$R_{MODE\_LO}$			200		$k\Omega$
<b>LINEAR REGULATOR (CAP)</b>						
Output Current Limit	$I_{CAP}$	$V_{CAP} = 0V$	4			mA
LDO Output Voltage	$V_{LDO}$	MAX14627, $V_{CC} = 2.8V$	2.0	2.2	2.45	V
		MAX14628, $V_{CC} = 3.3V$	2.55	2.8	3.1	
LDO PSRR	$PSRR_{LDO}$	Noise from $V_{CC}$ to CAP, $f = 217Hz$ , $V_{CC} = 2.8V \pm 0.1V$ , $I_{CAP} = 300\mu A$ , MODE = high		100		dB
LDO Noise	$N_{LDO}$	$V_{CC} = 2.8V$ , $I_{MIC} = 300\mu A$ , $f = 100Hz$ to $4000Hz$		11		$\mu V_{RMS}$
LDO Turn-Off Time	$t_{LDO\_OFF}$	MAX14627, $V_{CC} = 2.8V$ , $R_L = 2k\Omega$ , $V_{CAP}$ from 90% to 10%		60		$\mu s$
		MAX14628, $V_{CC} = 3.3V$ , $R_L = 2k\Omega$ , $V_{CAP}$ from 90% to 10%		60		
Minimum Bypass Capacitance	$C_{OUT}$	(Note 3)	0.22			$\mu F$
<b>DIGITAL SIGNALS (MODE, SWD, DET)</b>						
Input Logic-High Voltage	$V_{IH}$		1.4			V
Input Logic-Low Voltage	$V_{IL}$				0.4	V
MODE Average Current	$I_{MODE\_LOW}$	Pulsing with 1/64 duty cycle from MODE terminal when MODE = low, DETIN = low (Note 4)			1	$\mu A$
MODE Input Resistance	$R_{MODE\_HI}$	When MODE = high, DETIN = low	120	220	380	$k\Omega$
MODE External Maximum Leakage	$I_{MODE\_LKG}$	When MODE = high-Z (Note 3)	-1		+1	$\mu A$
Output Logic-High Leakage Current (Open Drain)	$I_{OH\_LKG}$	$V_{OH} = 5V$			1	$\mu A$

# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### ELECTRICAL CHARACTERISTICS (continued)

( $V_{CC} = 2.5V$  to  $5.5V$  for MAX14627,  $V_{CC} = 3.1V$  to  $5.5V$  for MAX14628,  $C_{DETIN} < 100pF$ ,  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $V_{CC} = +3.6V$ ,  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Logic-Low Voltage	$V_{OL}$	$I_{SINK} = 1mA$			0.4	V
<b>DYNAMIC CHARACTERISTICS</b>						
MODE Maximum Load Capacitance	$C_{MODE}$	(Note 3)			200	pF
MIC Low-Power Mode On-Time	$t_{MICLPO}$			120		$\mu s$
MIC Low-Power Mode Period	$t_{MICLPP}$			8		ms
High-Z Detection Time	$t_{HIZDET}$			16		ms
MODE 0 $\rightarrow$ 1 Detection Time	$t_{MODE0-1}$			4		ms
MODE 1 $\rightarrow$ 0 Detection Time	$t_{MODE1-0}$			16		ms
DETIN Debounce Time	$t_{DIDEB}$	Falling edge		300		ms
SEND/END Debounce Time	$t_{SEDEB}$			30		ms
<b>ESD PROTECTION</b>						
MIC, DETIN		Human Body Model		$\pm 15$		kV
All Other Pins		Human Body Model		$\pm 2$		kV

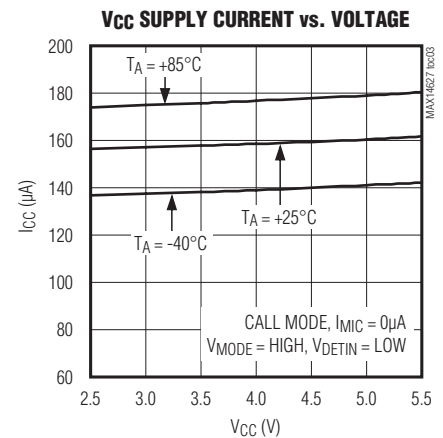
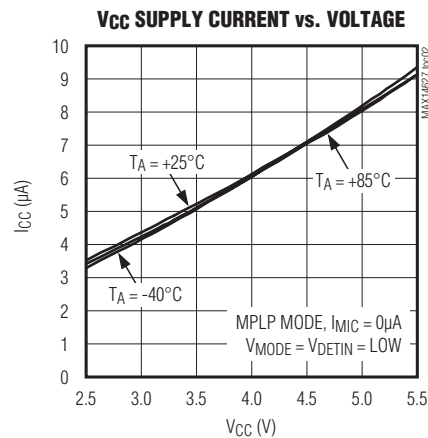
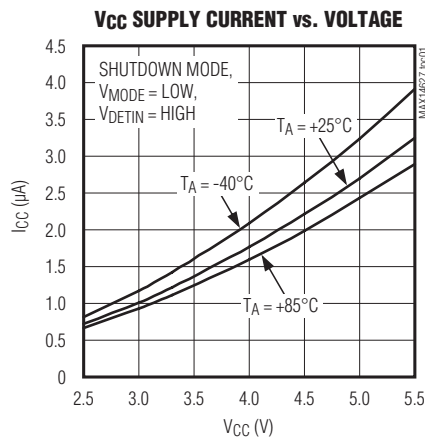
**Note 2:** All devices are production tested at  $T_A = +25^{\circ}C$ . Specifications over temperature are guaranteed by design.

**Note 3:** External specification requirements.

**Note 4:** Guaranteed by design.

### Typical Operating Characteristics

( $V_{CC} = 3.3V$ ,  $T_A = +25^{\circ}C$ ,  $C_{DETIN} < 100pF$ , unless otherwise noted.)

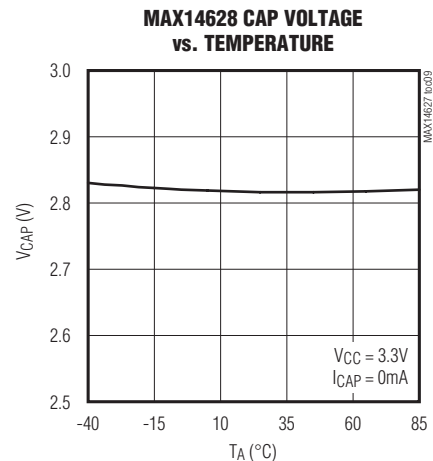
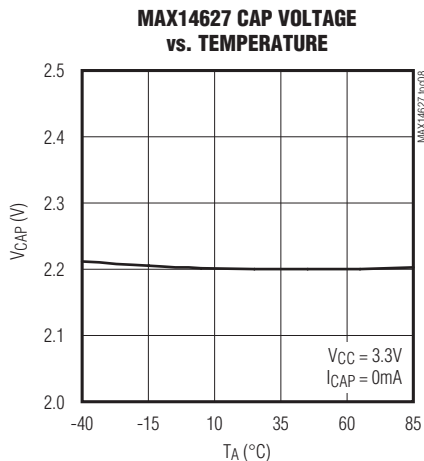
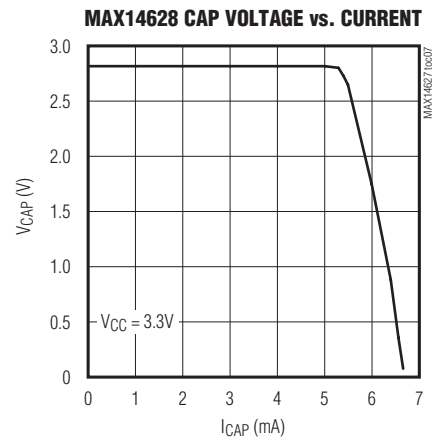
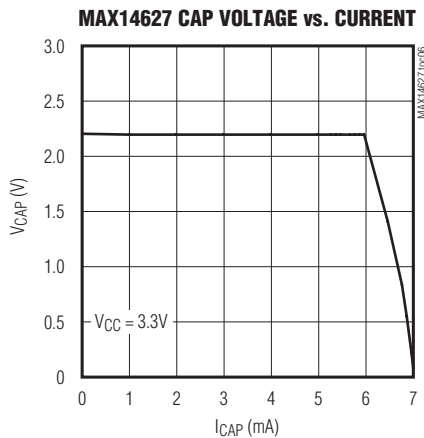
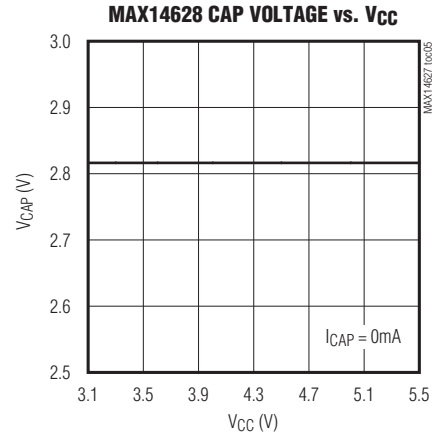
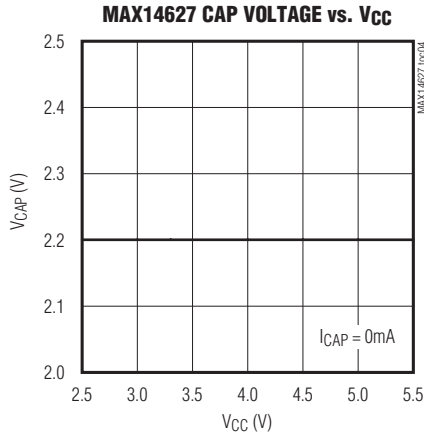


# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Typical Operating Characteristics (continued)

( $V_{CC} = 3.3V$ ,  $T_A = +25^\circ C$ ,  $C_{DETIN} < 100pF$ , unless otherwise noted.)

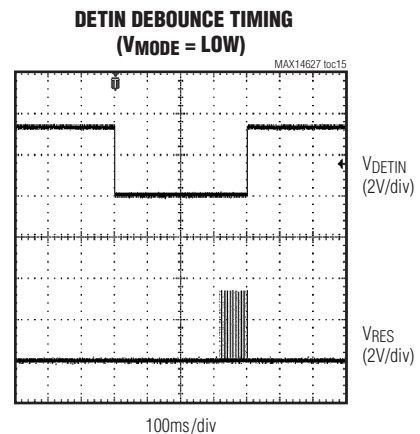
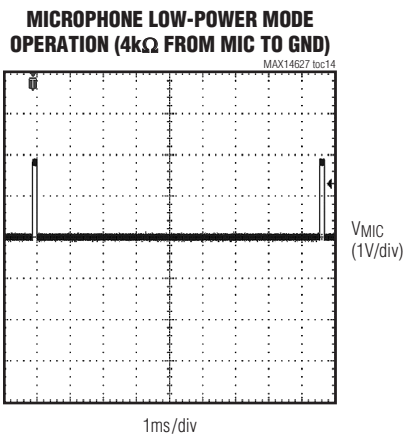
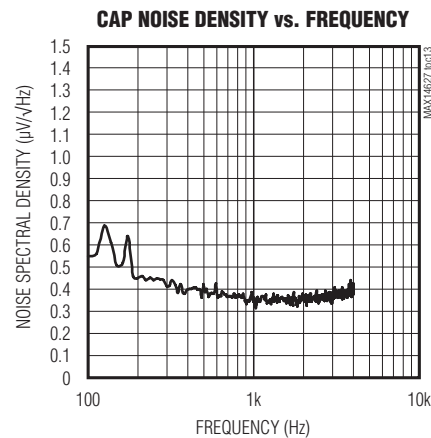
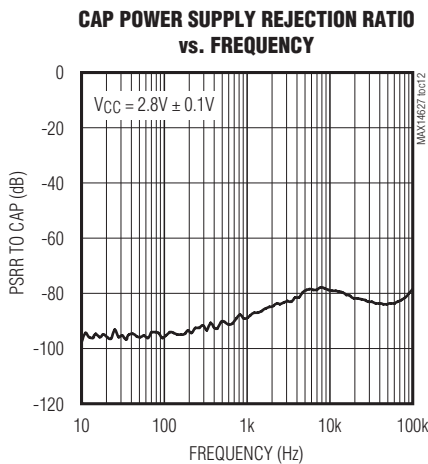
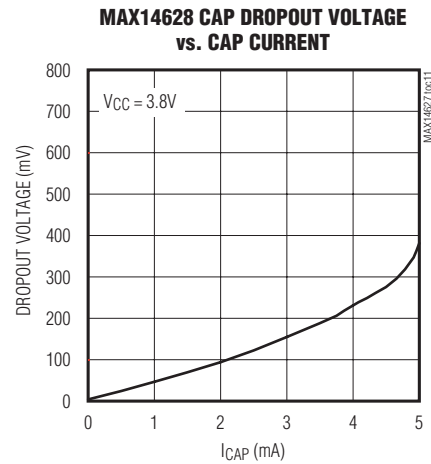
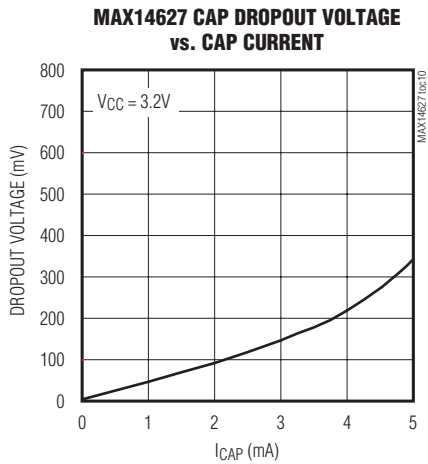


# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Typical Operating Characteristics (continued)

( $V_{CC} = 3.3V$ ,  $T_A = +25^\circ C$ ,  $C_{DETIN} < 100pF$ , unless otherwise noted.)

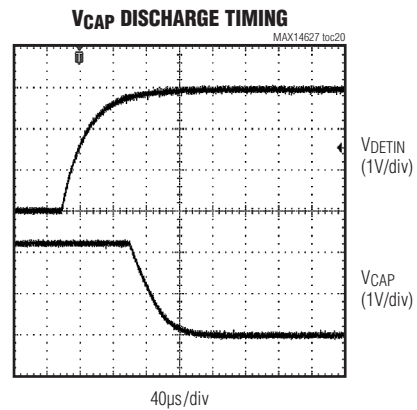
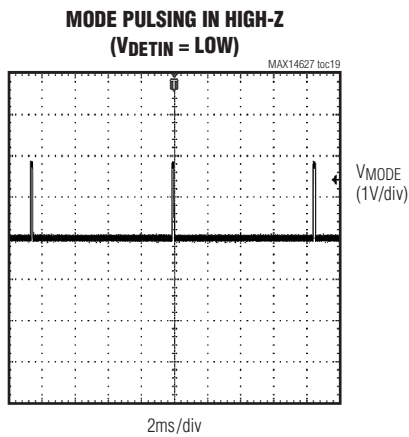
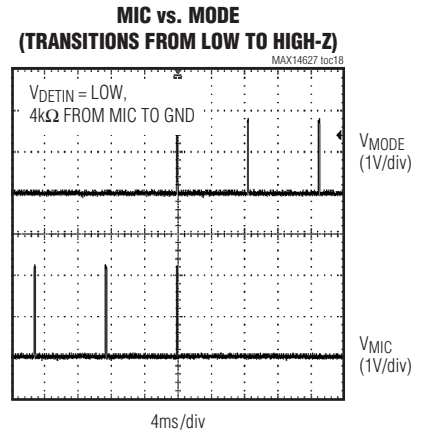
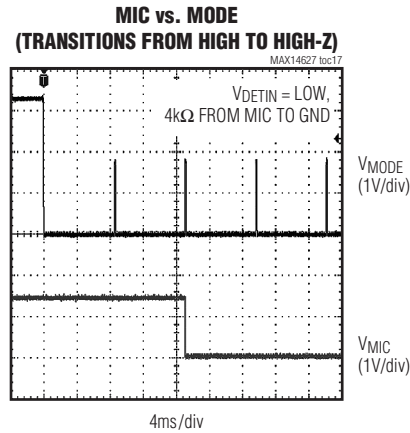
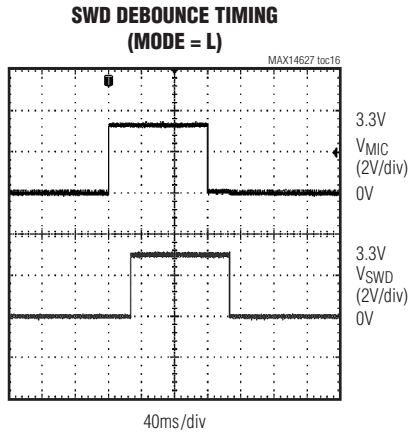


# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Typical Operating Characteristics (continued)

( $V_{CC} = 3.3V$ ,  $T_A = +25^\circ C$ ,  $C_{DETIN} < 100pF$ , unless otherwise noted.)

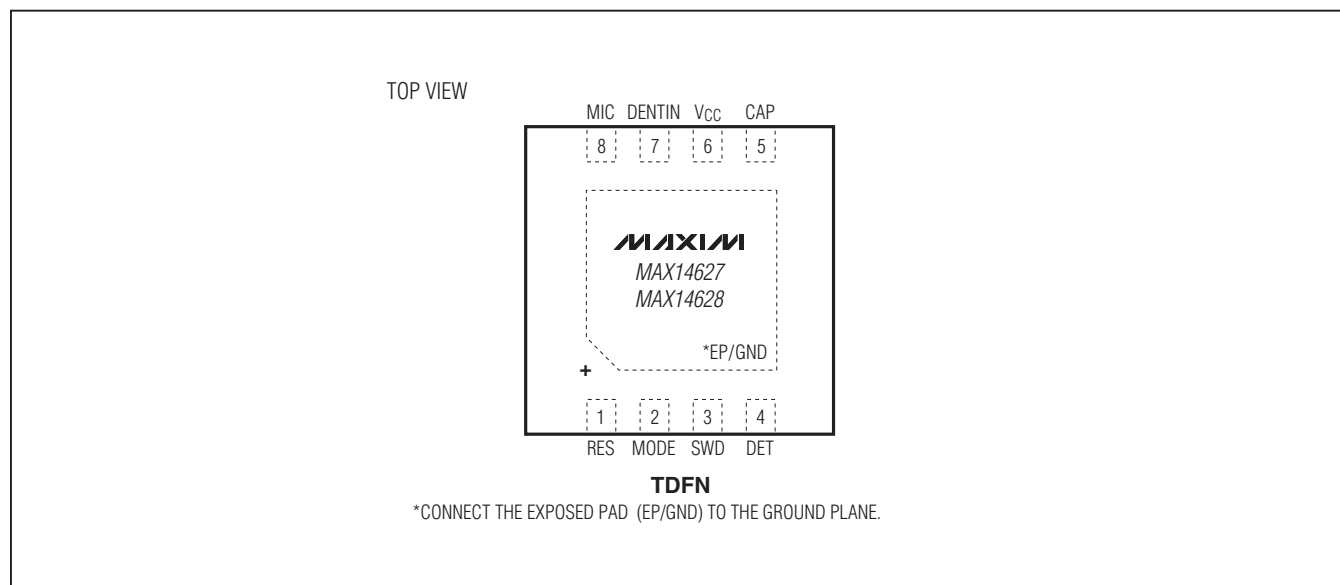




# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Pin Configuration



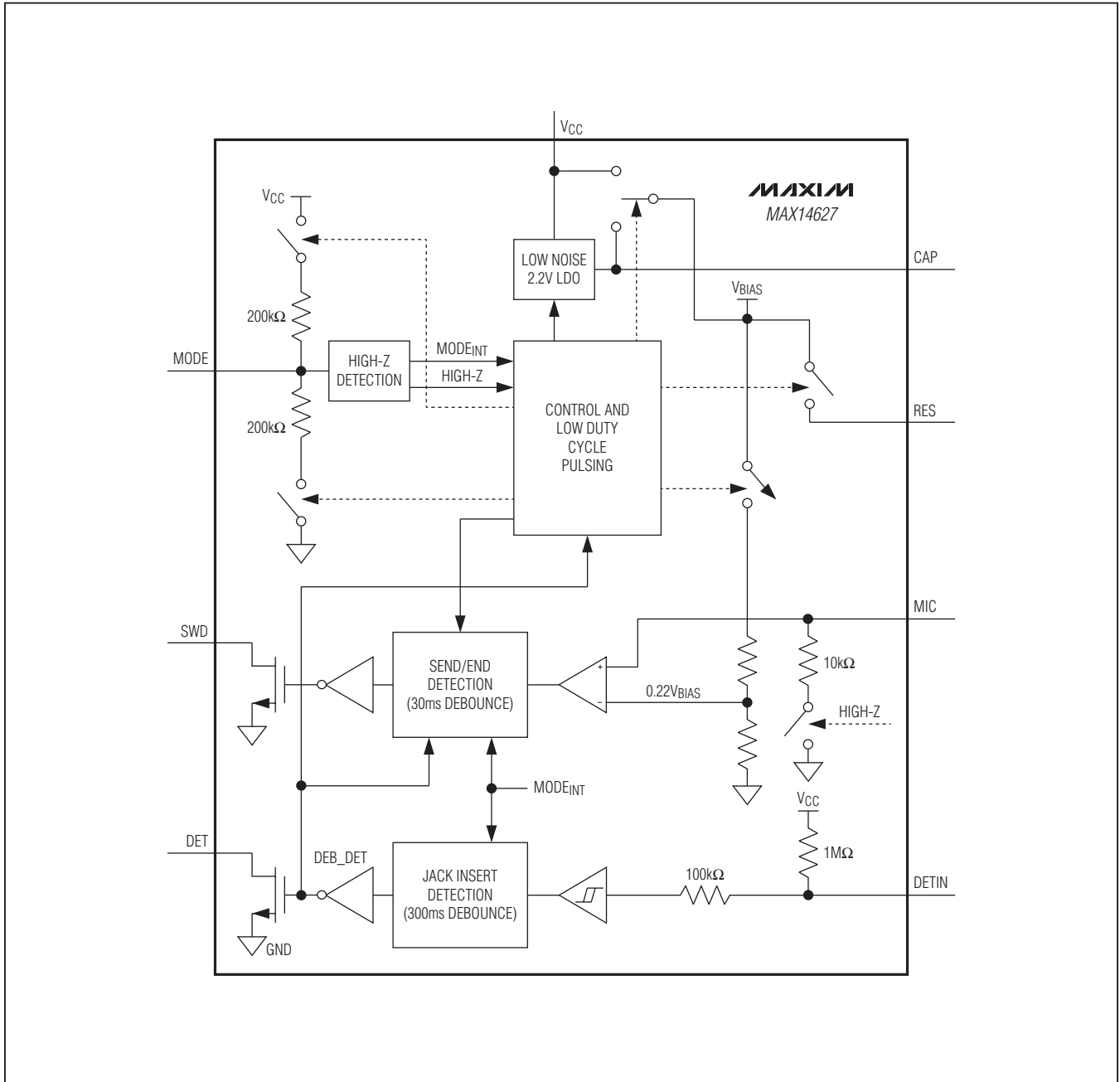
### Pin Description

PIN	NAME	FUNCTION
1	RES	Resistor Connection. Connect an external 2.2k $\Omega$ resistor from RES to MIC for microphone biasing.
2	MODE	Microphone Mode Selection Three-State Input. MODE selects the operating mode. See the <i>MODE Control Input</i> section for more information.
3	SWD	SEND/END Button Detection Output. SWD is an active-low, open-drain output.
4	DET	Jack Insertion Detection Output. DET is asserted when there is a 3.5mm jack inserted into the socket. DET is an active-low open-drain output.
5	CAP	Internal LDO Output. Connect a 1 $\mu$ F ceramic (X5R, X7R, or better) capacitor between CAP and ground as close as possible to the device.
6	V <sub>CC</sub>	Supply Voltage Input. Bypass V <sub>CC</sub> to ground with a 1 $\mu$ F ceramic capacitor as close as possible to the device.
7	DETIN	Jack Insertion Detection Input. An internal comparator monitors DETIN for jack insertion/removal events.
8	MIC	Microphone Connection Input. An internal comparator monitors MIC for SEND/END button press events.
—	EP/GND	Exposed Pad. The exposed pad is the ground connection for the device. Connect EP/GND to the ground plane.

# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

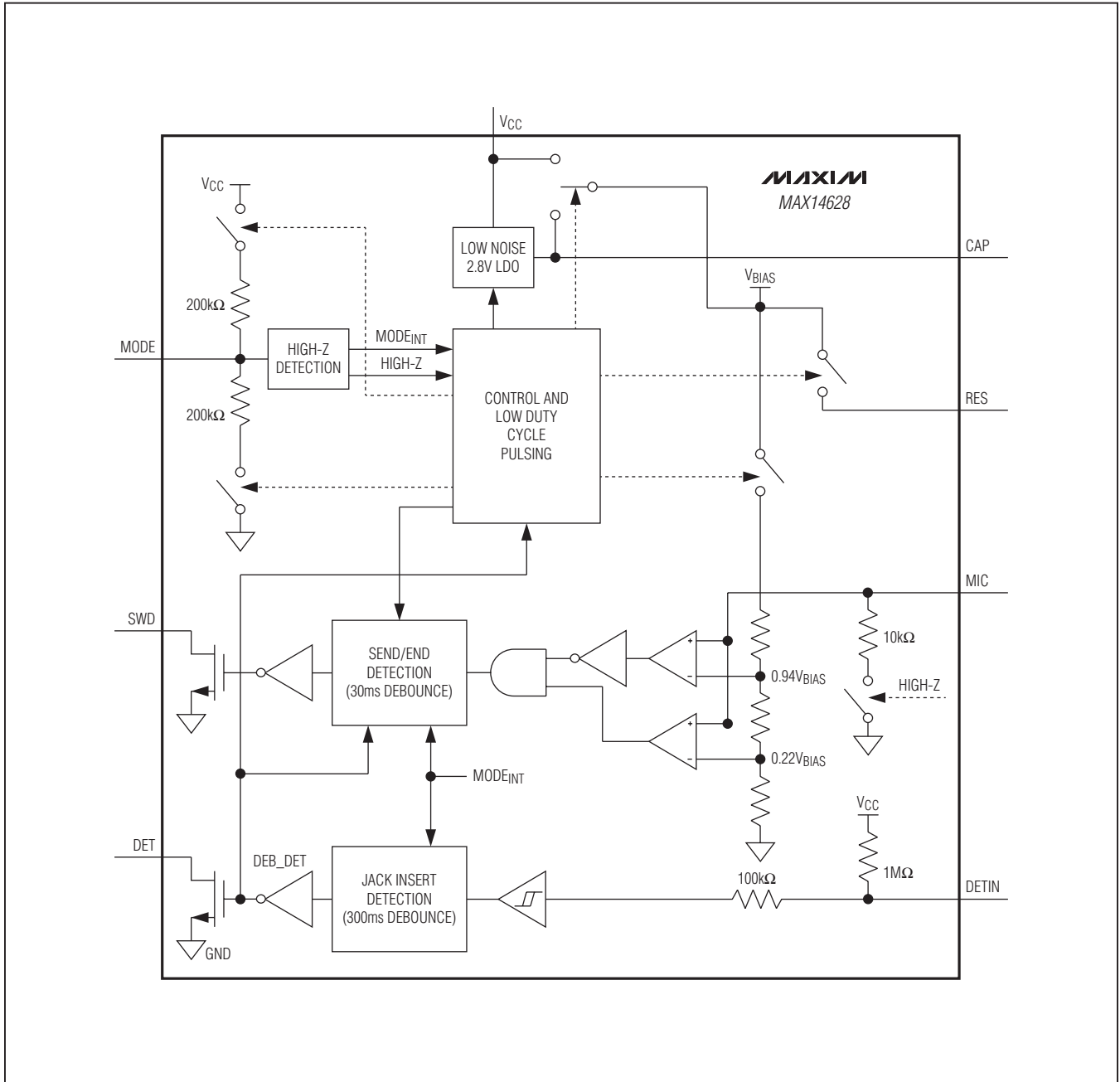
### MAX14627 Functional Diagram



# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

MAX14628 Functional Diagram



# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Detailed Description

The MAX14627/MAX14628 manage headsets by integrating 3.5mm jack insertion detection, microphone bias generation, and SEND/END button press detection. Both devices feature a low-power microphone mode to reduce the high bias current required for microphone operation while it is not in use. These devices require only a single three-state input (MODE) to select between call mode and two different low-power modes. See the *Internal LDO Regulator* and *SEND/END Button Press Detection* sections for details about the differences between these two devices.

### Internal LDO Regulator

The devices integrate a low-noise, low-dropout regulator (LDO) for biasing the microphone connected to MIC. The LDO output voltage is set at 2.2V for the MAX14627 and 2.8V for the MAX14628. The LDO is enabled and enters low-noise mode (LNM) when the MODE input is logic-high and a jack is detected (DETIN is low). Pull the MODE input low or leave it open to put the LDO in low-power shutdown mode (SDM).

Connect a 1 $\mu$ F capacitor from CAP to ground as close as possible to the pin.

### Microphone Operation and Bias Voltage Generation

An externally preamplified microphone is connected to MIC. Connect MIC to RES through an external 2.2k $\Omega$  resistor to bias the microphone.

The devices generate a bias voltage ( $V_{BIAS}$ ) at RES.  $V_{BIAS}$  is connected to the internal LDO when the LDO is on or connected to  $V_{CC}$  when the LDO is off.

### Microphone Low-Power Mode (MPLP)

A microphone draws a large amount of current due to the 2.2k $\Omega$  required bias resistor when it is connected. This current is dissipated even when the microphone is not in use for audio input. This allows the SEND/END button detection to operate. The devices feature internal circuitry to reduce this current while simultaneously detecting SEND/END button press events.

When a jack is inserted (DETIN is low and DET is asserted low) and if MODE is pulled low, these devices enter the microphone low-power mode (MPLP). In this mode,

MIC is periodically connected to  $V_{BIAS}$  ( $= V_{CC}$ ) through the 2.2k $\Omega$  resistor to RES only for a short duration (120 $\mu$ s pulse over an 8ms period) to check for the SEND/END button press event (switch to GND in both MAX14627/MAX14628 and switch open in the MAX14628 only).

The devices exit MPLP when the MODE input transitions to logic-high or to high-Z state.

Note that  $V_{BIAS}$  is disconnected from RES when no jack is inserted and microphone low-power mode is not entered.

### Jack Insertion Detection

The devices monitor the DETIN input to detect jack insertion/removal events. Debounce circuitry ensures that transient voltages do not force the device to enter or exit microphone low-power mode due to false jack insertion/removal detection. DETIN input is capable of handling  $\pm 15$ kV HBM ESD event.

The devices are designed for sockets with a normally open pin. Without the 3.5mm jack inserted at DETIN, the input is pulled high by a large internal pullup resistor (1M $\Omega$ ). When the jack is plugged in, DETIN is pulled to ground through the detection pin of the jack. DET is then asserted (after 300ms debounce time) and MIC is biased according to the logic state of the MODE input as follows:

- If MODE is low, the external 2.2k $\Omega$  resistor connects MIC to  $V_{CC}$  in pulsing mode (MPLP) waiting for a SEND/END button press event.
- If MODE is high, the external 2.2k $\Omega$  resistor connects MIC to LDO output continuously.
- If MODE is high-Z, MIC is internally pulled down.

The devices feature an internal series 100k $\Omega$  resistor at DETIN and do not require a series resistor between DETIN and the jack even when a direct drive audio output is connected to DETIN through the detection pin of the jack. DETIN withstands input voltages down to -2V.

Ensure that the total capacitance on DETIN is less than 100pF.

### SEND/END Button Press Detection

The devices monitor the MIC input to detect SEND/END button press events. The SEND/END button press with the 4P microphone headset is detected and pulls the SWD output low if the voltage at MIC falls below the MIC switch to GND detection threshold ( $0.22 \times V_{BIAS}$ ) for longer than 30ms.

# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

The MAX14628 also features an additional SEND/END detection mechanism through an additional MIC switch open detection threshold ( $0.94 \times V_{BIAS}$ ). If there is an open switch, then MIC is pulled up to  $V_{BIAS}$  in pulsing mode. If this happens for longer than 30ms, then the output SWD is pulled low.

The debounce period built into the SEND/END button press detection allows the mechanical SEND/END button to reach steady-state before applying the microphone bias. This mitigates click-and-pop noise.

The SEND/END detection circuitry is active whenever a jack is inserted (DETIN is low and DET is low).

### MODE High-Z State

If a 3P headset without a microphone is inserted, the SWD output is asserted low continuously. The user can turn off the microphone low-power mode by placing the MODE input to high-Z state after the recognition of a 3P jack. When in high-Z state, MODE is internally driven in pulsed mode.

### MODE Control Input

An external host processor controls the MODE input. Table 1 shows the behavior of these devices based on the MODE input and jack insertion status. The device enters call mode when the MODE pin is logic-high and a jack is detected, enabling the LDO immediately in low-noise mode (LNM). The LDO output powers  $V_{BIAS}$  and is connected to the microphone (MIC) through the external  $2.2k\Omega$  bias resistor.

Drive MODE low to put the devices in standby mode. In standby mode,  $V_{CC}$  powers  $V_{BIAS}$ , the LDO enters shut-down mode (SDM), and the microphone bias connection either turns off permanently if no jack is inserted or enters MPLP if a jack is inserted.

When MODE is set to high-Z, both the LDO and MPLP turn off. Also, the SWD output returns to a high-Z state, which can be used as a feedback of the device.

The MODE input is designed to be compatible with 1.8V logic when the  $V_{CC}$  is up to 5.5V. The MODE pin must be properly controlled based on DETIN status to avoid the click-and-pop noise due to a headset insertion.

## Applications Information

### Typical Connections for 3.5mm Jacks

There are two typical 3.5mm jacks: tip-ring-ring-sleeve (TRRS) with four conductors (Figure 1a) and tip-ring-sleeve (TRS) with three conductors (Figure 1b). The most common configuration of the TRRS jack is to use rings 1 and 2 for audio signals, ring 3 for ground, and ring 4 for a microphone. The TRS jack typically uses rings 1 and 2 for audio signals and rings 3 and 4 as ground.

### Supported Accessories

All the devices support all standard configurations of headsets with a microphone and SEND/END button on a TRS or TRRS 3.5mm jack. Figure 2 shows the supported connections of the speakers, SEND/END button, and microphone to the jack.

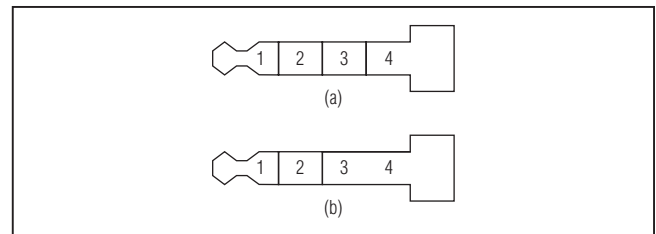


Figure 1. Typical 3.5mm Jacks

Table 1. Operating Modes

MODE	LOW		HIGH-Z		HIGH	
	Low	High	Low	High	Low	High
DETIN	Low	High	Low	High	Low	High
LDO Mode	SDM		SDM		LNM	SDM
MIC Bias Mode	MPLP	Off	Off*	Off	$2.2k\Omega$	Off

\*MIC is internally pulled down.

# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Headset with No Microphone

When the 3.5mm jack in Figure 2a is inserted, the MIC input is pulled low permanently by the ground connection on the sleeve and the SWD output is logic-low permanently. This type of headset is supported by implementing a timeout period in software to recognize that the permanent SWD logic-low state is not due to a very long SEND/END button press event. In this case, the MODE input pin can be placed in high-Z state to disable the pulsing on the MIC pin (MPLP) and set the SWD output in high-Z state.

### Headset with Microphone and Normally Open SEND/END Button in Parallel

When the 3.5mm jack in Figure 2b is inserted, the MIC input is pulled below the threshold only during a SEND/END button press event. The SWD output is logic-low when the SEND/END button is pressed for more than the 30ms (typ) debounce time.

### Headset with Normally Open SEND/END Button and Resistive Remote Control

The devices support the 3.5mm jack with a microphone and two buttons in Figure 2c that is the standard Windows Mobile configuration. The threshold is set to detect a button press, regardless of which button is pressed.

### Headset with Microphone and Normally Closed SEND/END Button in Series

The MAX14628 supports the 3.5mm jack with a microphone and a normally closed series switch. When the switch opens for more than the 30ms (typ) debounce time (SEND/END button press event), the SWD output asserts low.

### High-ESD Protection

Electrostatic discharge (ESD)-protection structures are incorporated on all pins to protect against electrostatic discharges up to  $\pm 2\text{kV}$  Human Body Model (HBM) encountered during handling and assembly. DETIN and MIC are further protected against ESD up to  $\pm 15\text{kV}$  (HBM) without damage. After an ESD event, all the devices continue to function without latching.

### ESD Test Conditions

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

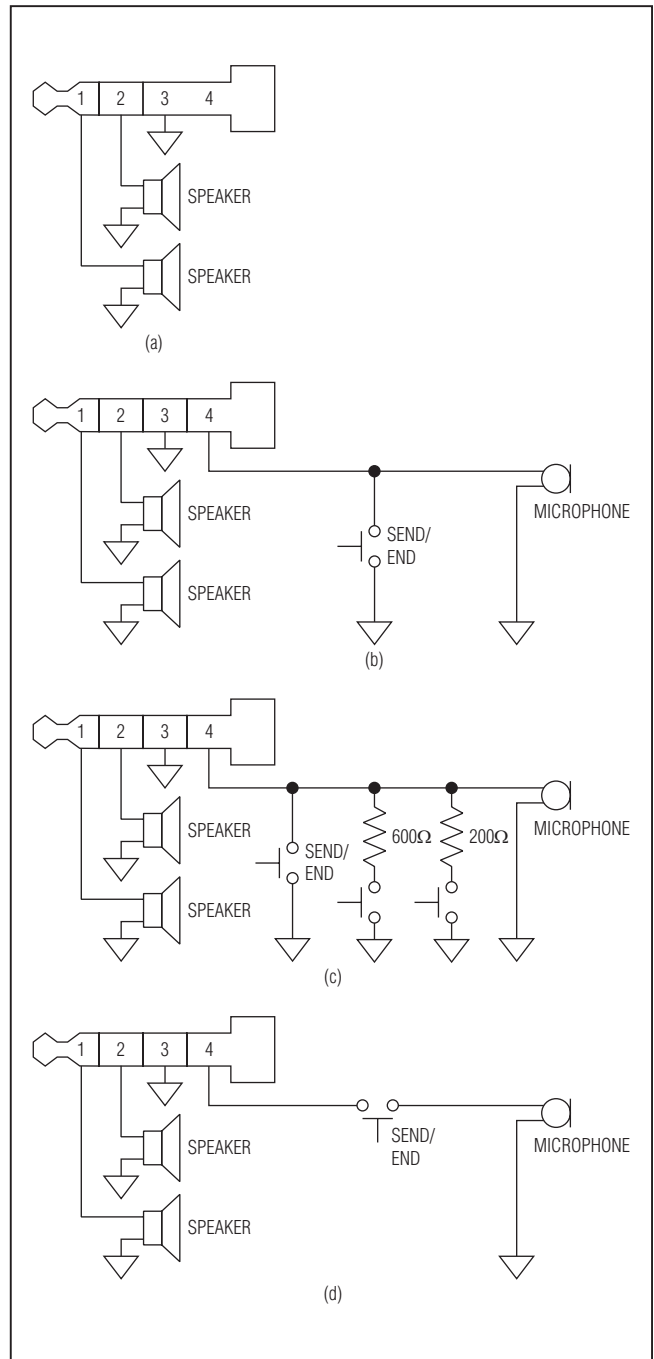
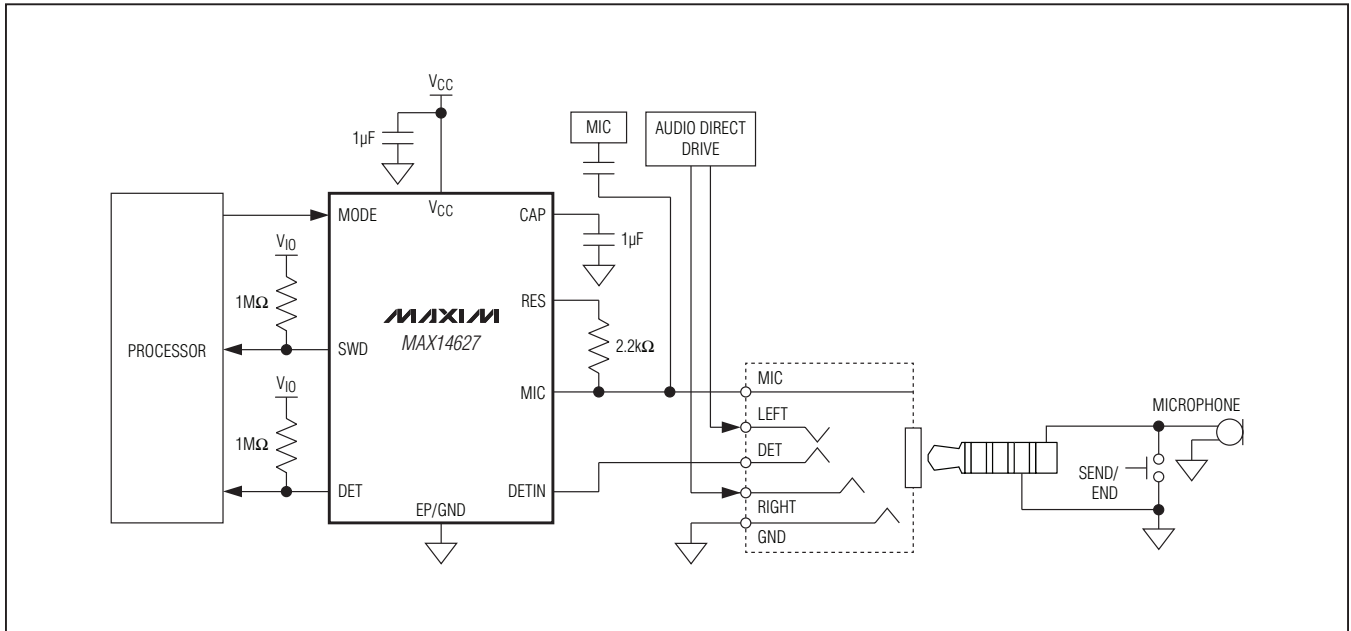


Figure 2. Supported 3.5mm Accessory Configurations

# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Typical Operating Circuits (continued)



# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX14627ETA+T	-40°C to +85°C	8 TDFN-EP*
MAX14628ETA+T	-40°C to +85°C	8 TDFN-EP*

+ Denotes a lead(Pb)-free/RoHS-compliant package.

T = Tape and reel.

\*EP = Exposed pad.

### Chip Information

PROCESS: BiCMOS

### Package Information

For the latest package outline information and land patterns (footprints), go to [www.maxim-ic.com/packages](http://www.maxim-ic.com/packages). Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
8 TDFN-EP	T822+2	<a href="#">21-0168</a>	<a href="#">90-0065</a>



# MAX14627/MAX14628

## Low-Power Headset Detectors with SEND/END Button Support

### *Revision History*

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	5/12	Initial release	—

*Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time. The parametric values (min and max limits) shown in the Electrical Characteristics table are guaranteed. Other parametric values quoted in this data sheet are provided for guidance.*

**Maxim Integrated Products, 120 San Gabriel Drive, Sunnyvale, CA 94086 408-737-7600 \_\_\_\_\_ 16**